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ABSTRACT



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A curable flux which works as a flux during soldering and as a reinforcing material for the soldered portion after being cured by heating; a resist for soldering which coats a circuit pattern having a land for placing solder balls and is cured by heating after the soldering; a semiconductor package and a semiconductor device in which the curable flux is used for soldering and the soldered portion is reinforced with the flux by heating; processes for producing a semiconductor package and a semiconductor device comprising using the curable flux for soldering and curing the curable flux after the soldering to reinforce the soldered portion. The curable flux works as a flux during bonding solder balls to the semiconductor package and soldering the package to a printed circuit board and reinforces the soldered portion after being cured by heating after the soldering.